Abstract of the Disclosure

A process for producing a large number of semiconductor chips from a semiconductor wafer having a large number of rectangular areas defined by streets arranged on the front surface in a lattice form, semiconductor circuits being formed in the respective rectangular areas. This process comprises the steps of forming a plurality of grooves having a predetermined depth in the back surface of the semiconductor wafer, grinding the back surface of the semiconductor wafer to reduce the thickness of the semiconductor wafer to a predetermined value and thereafter, cutting the semiconductor wafer along the streets to separate the rectangular areas from one another to obtain semiconductor chips.

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